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System in Package Market by Packaging Technology (2D IC, 2.5D IC, 3D IC), Package Type (BGA, SOP), Packaging Method (Flip Chip, Wire Bond), Device (RF Front-End, RF Amplifier), Application (Consumer Electronics, Communications) - Global Forecast to 2023

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Abstracts

"System in package market expected to grow at a significant rate between 2017 and 2023"

The system in package market is expected to grow from USD 5.79 billion in 2017 to USD 9.07 billion by 2023, at a CAGR of 9.4% during 2017–2023. The key factors driving the growth of the system in package market are the development strategies such as product launches and developments, mergers and acquisitions, expansions, agreements, collaborations, joint ventures, and partnerships implemented by the players operating in the system in package market, growing demand for miniaturization of electronic devices, and impact of Internet of Things (IoT). However, the major restraining factors for the growth of this market is the higher level of integration that leads to thermal issues.

"3D IC expected to grow at the highest CAGR of the system in package market on the basis of packaging technology during the forecast period"

The 3D IC market is expected to grow at the highest CAGR during the forecast period. The compact structure of 3D IC packaging technology further increases its demand in various smart technologies. Moreover, the major factors driving the system in package market for 3D IC packaging technology include the highest interconnect density and

greater space efficiencies in 3D IC compared with all other types of packaging technology such as 2D and 2.5 D.

“Consumer electronics application expected to hold the largest share of the overall system in package market in 2017”

Smartphones and tablets are observed to have the highest adoption among all the consumer electronic devices owing to their small form factor and better performance requirements to operate at a higher bandwidth. As a result, many ICs need to be incorporated into a single chip module for reducing the board space while considering cost and the overall time-to-market. In addition, consumer electronics products, such as mobile phones, tablets, netbook PCs, digital video cameras, and gaming controllers are adopting the advanced architecture. These products address features that increase the demand for miniaturized electronic devices with improved performance in consumer electronics. Owing to these factors, the consumer electronics application expected to hold the largest share of the overall system in package market in 2017.

“System in package market in APAC expected to hold the largest share in 2017”

The overall system in package market in APAC is expected to hold the largest share in 2017, and because of the presence of major IC packaging and wafer suppliers in this region. This makes the integration of 2D, 2.5D, and 3D IC packaging technology in APAC much easier.

The break-up of the profiles of primary participants for the report has been given below.

By Company Type: Tier 1 = 45%, Tier 2 = 30%, and Tier 3 = 25%

By Designation: C-Level Executives = 40% and Managers = 60%

By Region: Americas = 35%, APAC = 45%, Europe = 15%, and RoW = 5%

ASE Group (Taiwan), Amkor Technology (US), SPIL (Taiwan), Powertech Technology (Taiwan), UTAC (Global A&T Electronics) (Singapore), Intel (US), Samsung Electronics (South Korea), JCET (China), Chipmos Technologies (Taiwan), Chipbond Technology (Taiwan), KYEC (Taiwan), Texas Instruments (US), Signetics (South Korea), Unisem (Malaysia), Carsem (Malaysia), FATC (Taiwan), Inari Amertron Berhad (Malaysia), Ardentec (Taiwan), Alchip (Taiwan), Hana-Micron (South Korea), OSE (Taiwan),

Greatek Electronics (Taiwan), Tainshui Huatian Technology (China), AOI Electronics (Japan), Lingsen Precision Industry (Taiwan), Nepes (South Korea), Tongfu Microelectronics (China), and Sigurd Microelectronics (Taiwan) are the key players operating in the system in package market.

Research Coverage:

The research report on the system in package market covers the market segmented on the basis of the following segments: packaging technology, package type, packaging method, device, application, and geography. The market has been segmented on the basis of packaging technology into 2D, 2.5D, and 3D IC. Based on package type, the system in package market has been classified into ball grid array, surface mount package, pin grid array, flat package, and small outline package. The market has been segmented on the basis of packaging method into wire bond and die attach, flip chip, and fan-out wafer level packaging. Based on device, the system in package market has been classified into RF front-end, RF power amplifier, PMIC, MEMS, application processor, baseband processor, and others. The market on the basis of application has been segmented into consumer electronics, communications, automotive & transportation, industrial, aerospace & defense, healthcare, and emerging and others.

Key Benefits of Buying the Report:

Illustrative segmentation, analysis, and forecast for the market on the basis of packaging technology, package type, packaging method, device, application, and geography have been conducted to give the overall view of the system in package market.

The value chain analysis is provided to provide an in-depth insight into the system in package market.

The major drivers, restraints, opportunities, and challenges for the system in package market have been detailed in this report.

The report includes a detailed competitive landscape, in-depth DIVE analysis, and revenue of the key players.

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